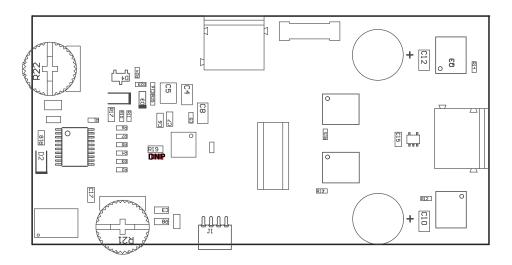
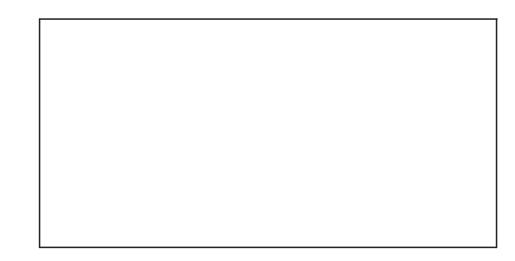
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ3 

  These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00620	REV: E1	SUN REV	: Not In VersionControl
	TID #: TIDA-00620			
PLOT NAME = Top Assembly Drawing	GENERATED : 10/5/201	15 3:07:18	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00620 REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-00620	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/5/2015 3:07:19	PM TEXAS INSTRUMENTS

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